



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

## PRODUCT CHANGE NOTIFICATION

**PCN:** PCN173903

**Date:** October 01, 2017

**Subject:** Qualification of Texas Instruments' DMOS 6 as an Additional Wafer Fab Site, Cypress's Test 25 as an Additional Wafer Sort Site, and Copper-Palladium Wire for Select 512kb/1Mb Serial F-RAM Industrial-Grade Products

**To:** TOKYO ELECTRON DEVICE

**Change Type:** Major

### Description of Change:

Cypress announces the qualification of TI's DMOS 6 as an additional wafer fab site and Cypress's Test 25 as an additional wafer sort site for select 512kb/1Mb serial industrial-grade F-RAM products. Cypress also announces the qualification of Copper-Palladium (CuPd) wire bond for the 8-Lead SOIC package for select 512kb/1Mb serial industrial-grade F-RAM products at United Test and Assembly Center Co., Ltd. (UTAC), Thailand, using the Bill of Materials shown below:

Material	Au Wire	CuPd Wire
Mold Compound	Sumitomo G600	Sumitomo G600
Lead Finish	Matte Sn	Matte Sn
Die Attach Epoxy	Henkel 8200T	Henkel 8200T
Wire Diameter	0.8 mil	0.8 mil
Bond Wire	Au	CuPd

### Benefit of Change:

Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

All three of these changes must be qualified simultaneously in order to ensure continuity of supply given the tight capacity situation. DMOS 6, Test 25, and CuPd wires are already being used to fabricate, sort and assemble other FRAM products in densities ranging from 4kb to 2Mb; the assembly site remains UTAC.

**Part Numbers Affected: 3**

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

**Qualification Status:**

The additional wafer fab and wafer sort sites have been qualified through a series of tests documented in Qualification Test Plans (QTP) 163901 and 170503. The 8-lead SOIC package with CuPd wire has been qualified through a series of tests documented in QTP 140502. These qualification reports can be found as attachments to this PCN or by visiting [www.cypress.com](http://www.cypress.com) and typing the QTP number in the keyword search window.

**Sample Status:**

Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated DMOS 6 and CuPd wire sample ordering part numbers. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, and no later than 30 days from the date of this PCN, to place your order.

**Approximate Implementation Date:**

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of the affected part numbers in the attached file will be supplied from DMOS6 or other approved wafer fabrication sites, will be sort tested at Test 25 or other approved wafer sort sites, and will transition to CuPd wire.

**Anticipated Impact:**

Products fabricated at DMOS 6 and assembled with CuPd wire are completely compatible with existing products from a functional, parametric, and quality performance perspective.

**Method of Identification:**

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package and through a revision letter on the die.

**Response Required:**

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at [pcn\\_adm@cypress.com](mailto:pcn_adm@cypress.com).

Sincerely,

Cypress PCN Administration